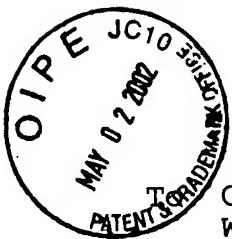


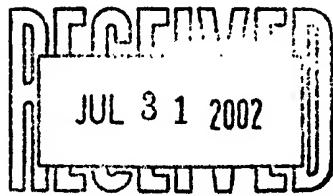
STATS-01-005



April 26, 2002

Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603



Subject:

Serial No. 10/083,993 02/26/02

Jeffrey D. Punzalan et al.

GROUND PLANE FOR EXPOSED PACKAGE

Grp. Art Unit: 2811

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner of Patents and
Trademarks, Washington, D.C. 20231, on April 29, 2002.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

Stephan B. Ackerman 4/29/02

U.S. Patent 6,300,673 to Hoffman et al., "Edge Connectable Metal Package," discloses a die attach paddle and ground plane for a package.

U.S. Patent 6,284,571 to Corisis et al., "Lead Frame Assemblies with Voltage Reference Plane and IC Packages Including Same," describes a structure for a die attach paddle and ground plane for a package.

U.S. Patent 6,096,163 to Wensel, "Method and Apparatus for Application of Spray Adhesive to a Leadframe for Chip Bonding," discloses a process for adhesives to leadframe.

U.S. Patent 5,434,750 to Rostoker et al., "Partially-Molded, PCB Chip Carrier Package for Certain Non-Square Die Shapes," discloses a leadframe design.

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.